

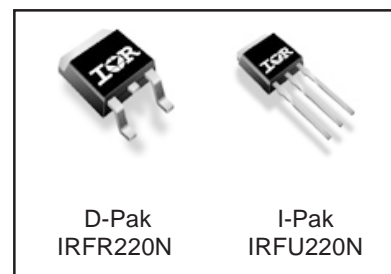
**Applications**

- High frequency DC-DC converters

$V_{DSS}$	$R_{DS(on)}$ max (m $\Omega$ )	$I_D$
200V	600	5.0A

**Benefits**

- Low Gate to Drain Charge to Reduce Switching Losses
- Fully Characterized Capacitance Including Effective  $C_{OSS}$  to Simplify Design, (See App. Note AN1001)
- Fully Characterized Avalanche Voltage and Current



**Absolute Maximum Ratings**

	Parameter	Max.	Units
$I_D$ @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS}$ @ 10V	5.0	A
$I_D$ @ $T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS}$ @ 10V	3.5	
$I_{DM}$	Pulsed Drain Current ①	20	
$P_D$ @ $T_C = 25^\circ\text{C}$	Power Dissipation	43	W
	Linear Derating Factor	0.71	W/ $^\circ\text{C}$
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
dv/dt	Peak Diode Recovery dv/dt ③	7.5	V/ns
$T_J$	Operating Junction and	-55 to + 175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case )	

**Typical SMPS Topologies**

- Telecom 48V input Forward Converters

Notes ① through ⑤ are on page 10

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# IRFR/U220N

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## Static @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	200	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔV <sub>(BR)DSS/ΔT<sub>J</sub></sub>	Breakdown Voltage Temp. Coefficient	—	0.23	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA ④
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance	—	—	600	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 2.9A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0	—	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	25	μA	V <sub>DS</sub> = 200V, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 160V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	100	nA	V <sub>GS</sub> = 20V
	Gate-to-Source Reverse Leakage	—	—	-100		V <sub>GS</sub> = -20V

## Dynamic @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g <sub>fs</sub>	Forward Transconductance	2.6	—	—	S	V <sub>DS</sub> = 50V, I <sub>D</sub> = 2.9A
Q <sub>g</sub>	Total Gate Charge	—	15	23	nC	I <sub>D</sub> = 2.9A
Q <sub>gs</sub>	Gate-to-Source Charge	—	2.4	3.6		V <sub>DS</sub> = 160V
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge	—	6.1	9.2		V <sub>GS</sub> = 10V,
t <sub>d(on)</sub>	Turn-On Delay Time	—	6.4	—	ns	V <sub>DD</sub> = 100V
t <sub>r</sub>	Rise Time	—	11	—		I <sub>D</sub> = 2.9A
t <sub>d(off)</sub>	Turn-Off Delay Time	—	20	—		R <sub>G</sub> = 24Ω
t <sub>f</sub>	Fall Time	—	12	—		V <sub>GS</sub> = 10V ④
C <sub>iss</sub>	Input Capacitance	—	300	—	pF	V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance	—	53	—		V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance	—	15	—		f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	300	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 1.0V, f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	23	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 160V, f = 1.0MHz
C <sub>oss eff.</sub>	Effective Output Capacitance	—	46	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V to 160V ⑤

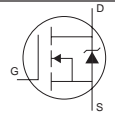
## Avalanche Characteristics

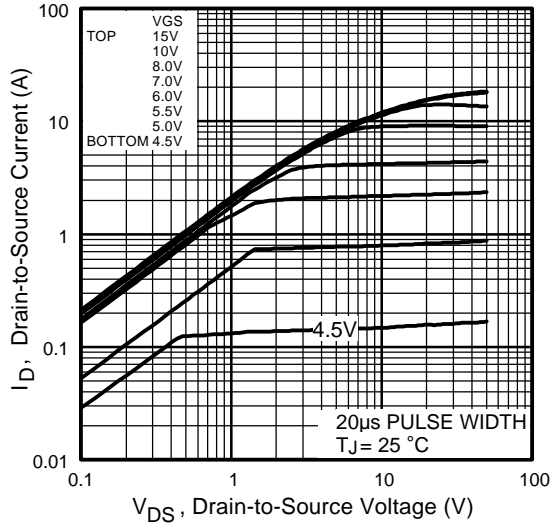
	Parameter	Typ.	Max.	Units
E <sub>AS</sub>	Single Pulse Avalanche Energy②	—	46	mJ
I <sub>AR</sub>	Avalanche Current①	—	2.9	A
E <sub>AR</sub>	Repetitive Avalanche Energy①	—	4.3	mJ

## Thermal Resistance

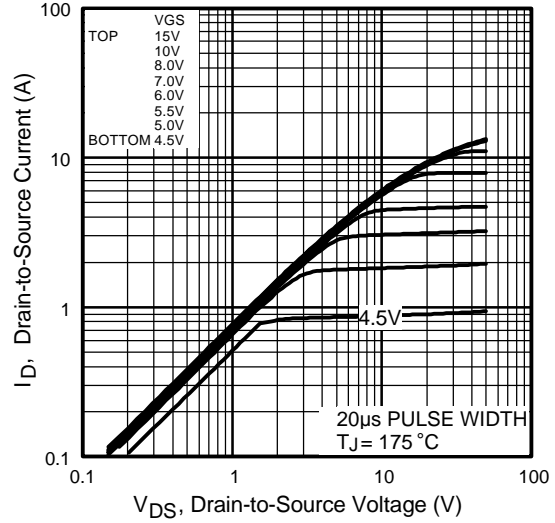
	Parameter	Typ.	Max.	Units
R <sub>θJC</sub>	Junction-to-Case	—	3.5	°C/W
R <sub>θJA</sub>	Junction-to-Ambient (PCB mount)*	—	50	
R <sub>θJA</sub>	Junction-to-Ambient	—	110	

## Diode Characteristics

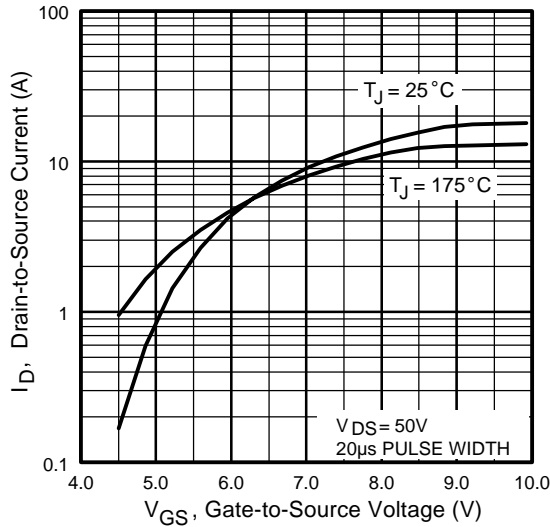
	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	5.0	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①	—	—	20		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.3	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 2.9A, V <sub>GS</sub> = 0V ④
t <sub>rr</sub>	Reverse Recovery Time	—	90	140	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 2.9A
Q <sub>rr</sub>	Reverse Recovery Charge	—	320	480	nC	di/dt = 100A/μs ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )				



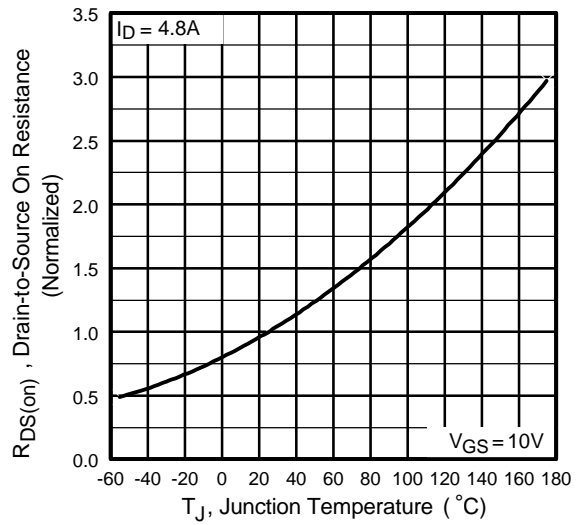
**Fig 1.** Typical Output Characteristics



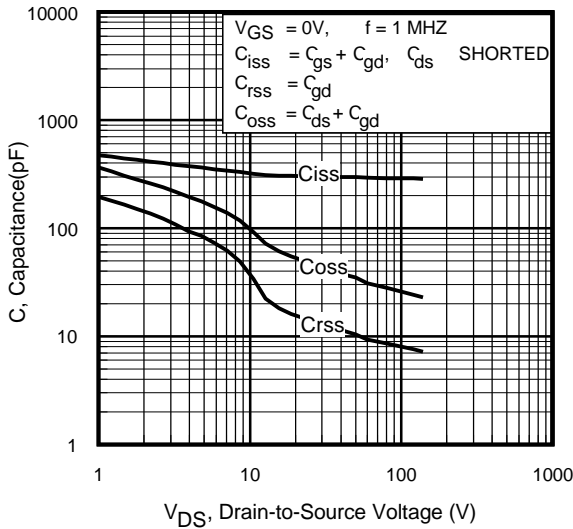
**Fig 2.** Typical Output Characteristics



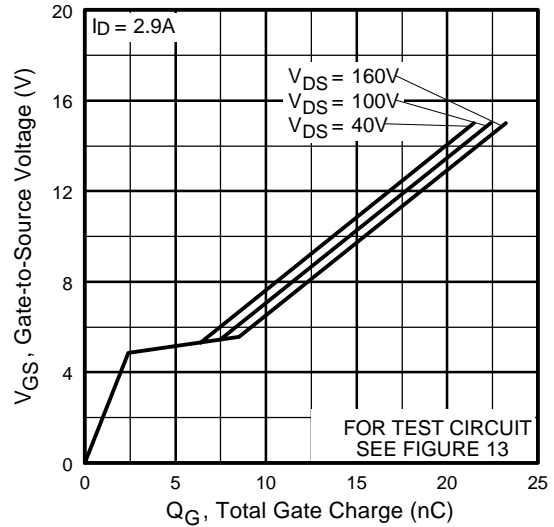
**Fig 3.** Typical Transfer Characteristics



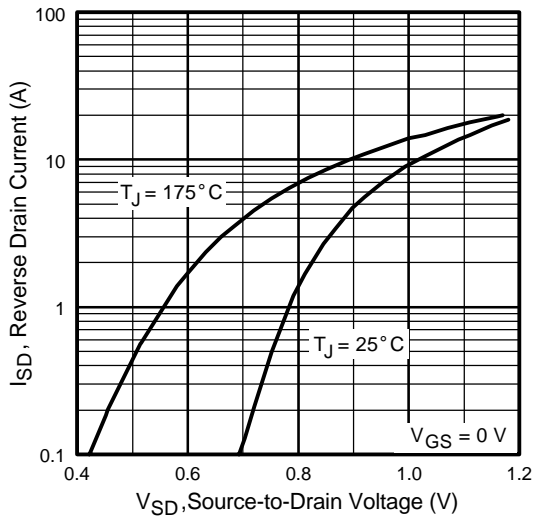
**Fig 4.** Normalized On-Resistance Vs. Temperature



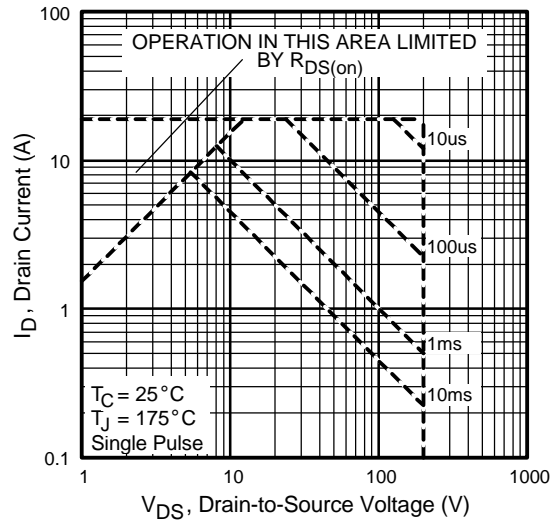
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 8.** Maximum Safe Operating Area

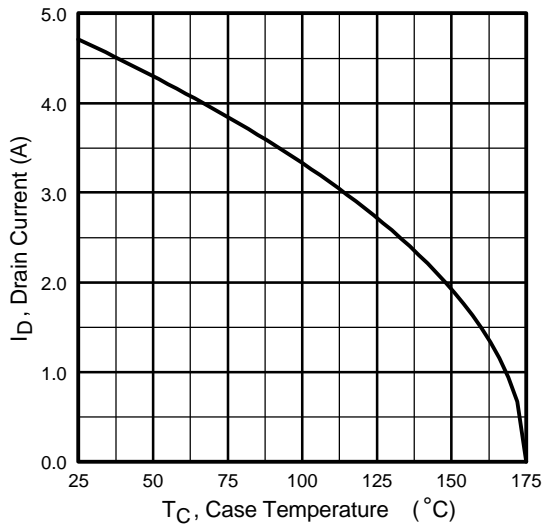


Fig 9. Maximum Drain Current Vs. Case Temperature

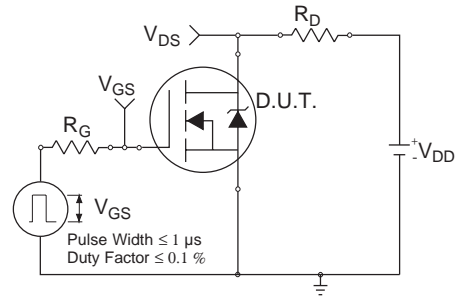


Fig 10a. Switching Time Test Circuit



Fig 10b. Switching Time Waveforms

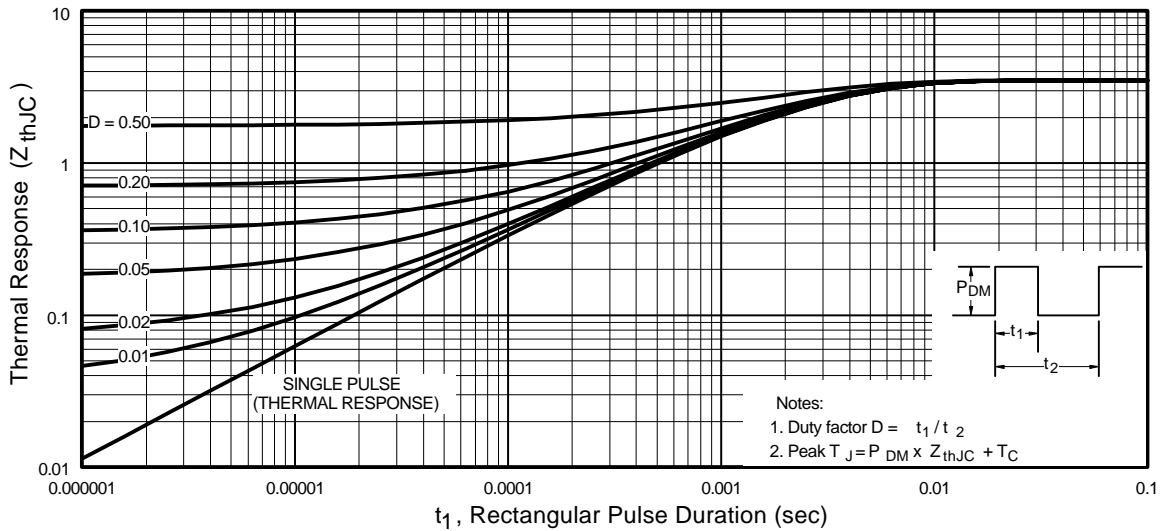
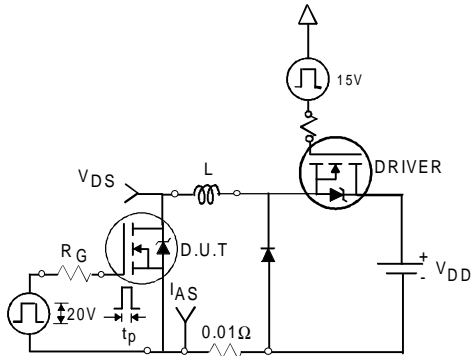
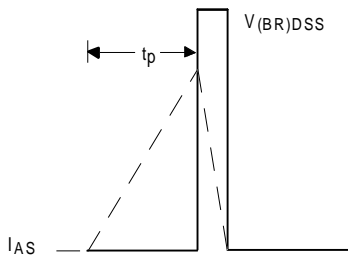


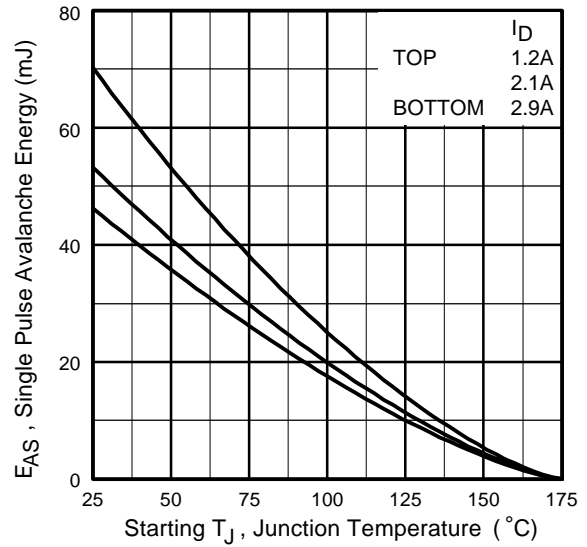
Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



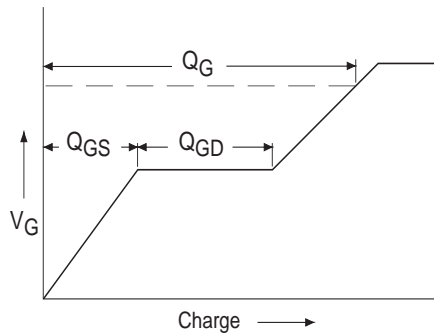
**Fig 12a.** Unclamped Inductive Test Circuit



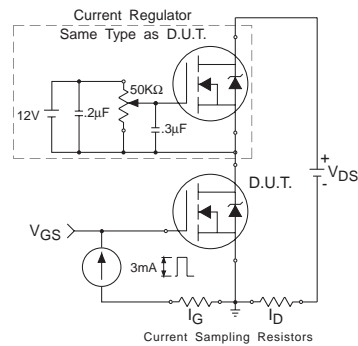
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current

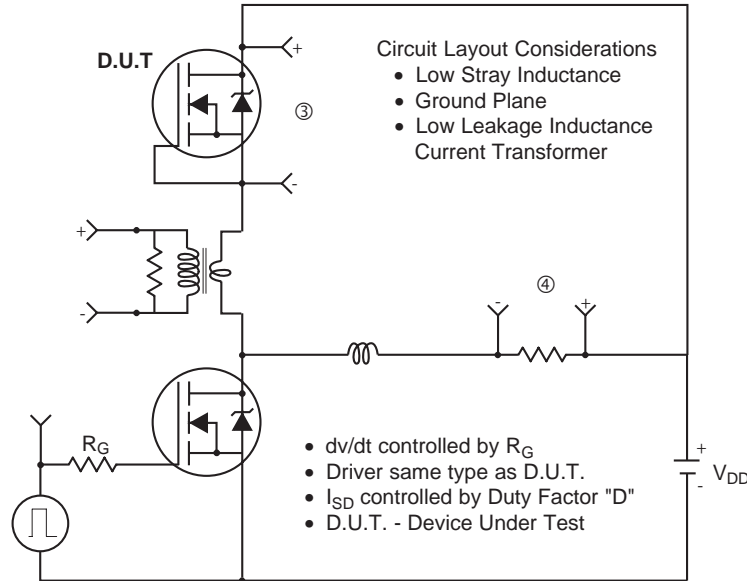


**Fig 13a.** Basic Gate Charge Waveform



**Fig 13b.** Gate Charge Test Circuit

**Peak Diode Recovery dv/dt Test Circuit**



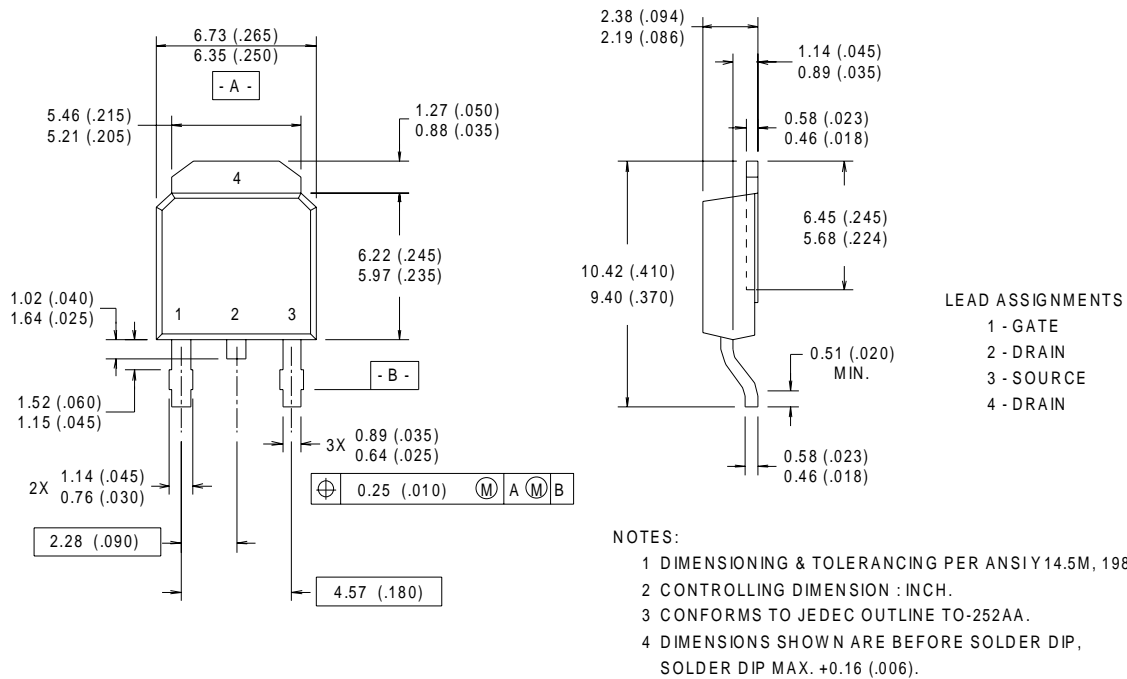
\*  $V_{GS} = 5V$  for Logic Level Devices

**Fig 14.** For N-Channel HEXFET® Power MOSFETs

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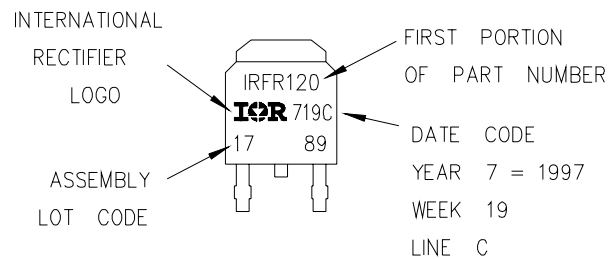
## D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



## D-Pak (TO-252AA) Part Marking Information

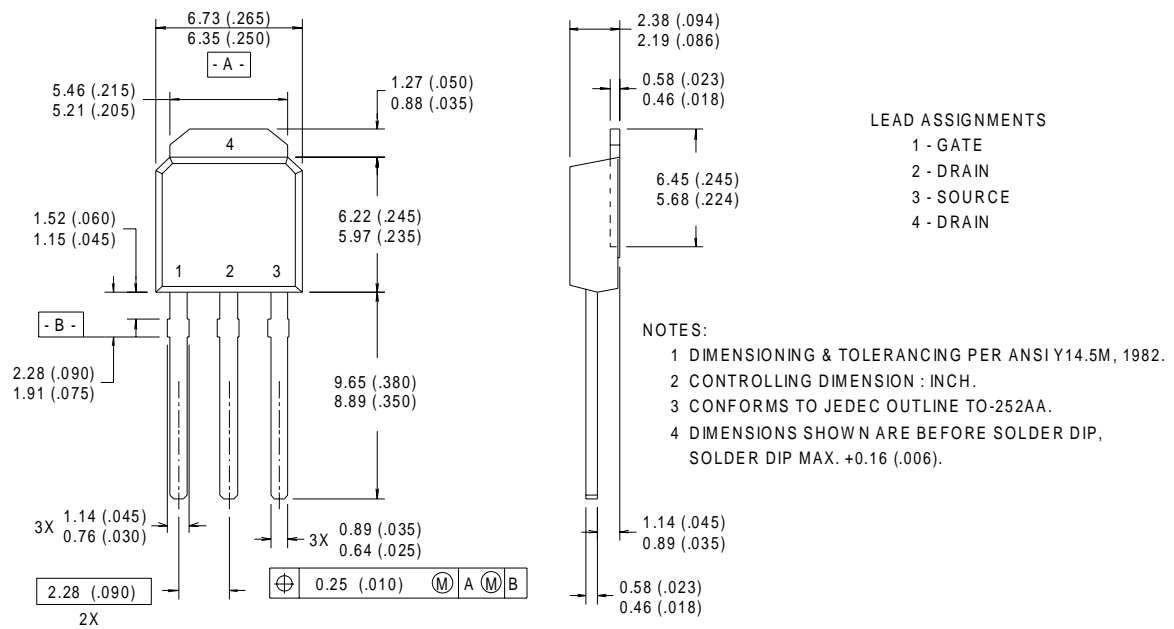
EXAMPLE: THIS IS AN IRFR120  
 LOT CODE 1789  
 ASSEMBLED ON WW 19, 1997  
 IN THE ASSEMBLY LINE "C"





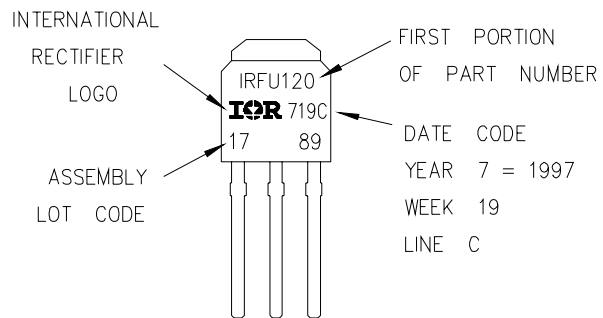
## I-Pak (TO-251AA) Package Outline

Dimensions are shown in millimeters (inches)



## I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120  
 LOT CODE 1789  
 ASSEMBLED ON WW 19, 1997  
 IN THE ASSEMBLY LINE "C"

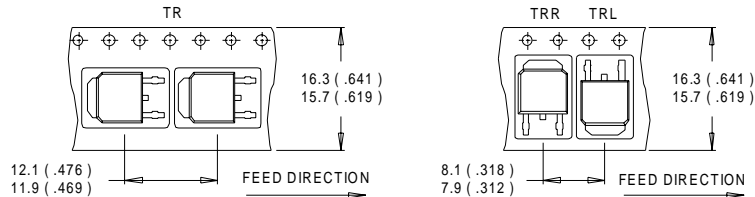


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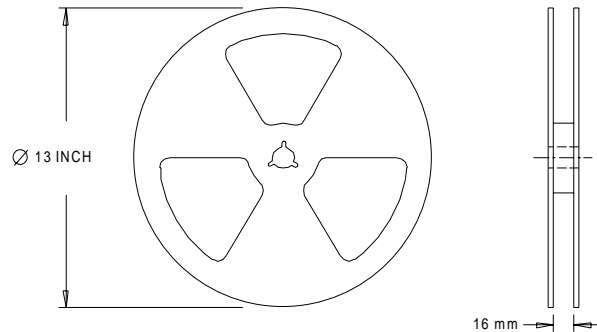
## D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



**NOTES :**

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS ( INCHES ).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



**NOTES :**

1. OUTLINE CONFORMS TO EIA-481.

**Notes:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
  - ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 11\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 2.9\text{A}$ .
  - ③  $I_{SD} \leq 2.9\text{A}$ ,  $di/dt \leq 320\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  
 $T_J \leq 175^\circ\text{C}$
  - ④ Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
  - ⑤  $C_{oss}$  eff. is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$
- \* When mounted on 1" square PCB (FR-4 or G-10 Material).  
For recommended footprint and soldering techniques refer to application note #AN-994.

International  
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TAC Fax: (310) 252-7903

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*Data and specifications subject to change without notice. 11/00*

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